Rocktech Displays Limited



Module P/N: RK013BF001A0

Version: 1.0

Description: 1.3 inch TFT 240*240 Pixels with

LED backlight, All viewing angle,

400 nits brightness

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Revision History

Date	Rev.	Page	Description
2020-05-10	1.0	All	First issue



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1. General Features

Item	Spec	Remark
Display Mode	Normally Black transmissive	
Viewing Direction	FREE	IPS
Input Signals	MCU	
Outline Dimensions(mm)	26.20(W) x 29.22(H) x1.46(D)	
Active Area(mm)	23.40mm(W)×23.40mm(H)	
Number of Pixels	240(RGB)×240	
Dot Pitch(mm)	0.0975mm(W) × 0.0975mm(H)	
Pixel Arrangement	RGB Vertical stripes	
Drive IC	ST7789V	



2. Absolute Maximum Ratings

The following are maximum values which, if exceeded may cause operation or damage to the unit.

ITEM	Sym.	Min.	Тур.	Max.	Unit	Remark
Power for Circuit Driving	VCC	-0.3	-	4.6	V	
Logic Signal Input/output Voltage	Vddi	-0.3	-	4.6	V	
Storage Humidity	H _{ST}	10	-		%RH	
Storage Temperature	T _{ST}	-30	-	80	$^{\circ}\!\mathbb{C}$	At
Operating Ambient Humidity	H _{OP}	10	-		%RH	25±5 ℃
Operating Ambient temperature	T _{OP}	-20	-	70	$^{\circ}$	



3. Electrical Specification

3.1 Driving TFT LCD Panel

It	Sym.	Min	Тур.	Max	Unit	Note	
Power for (VCC	2.5	2.8	3.3	V		
Power for Circuit Logic		IOVCC	1.65	1.8	3.3	V	
Logic Input Voltage	Low Voltage	VIL	-0.3	-	0.2VCC	V	
	High Voltage	ViH	0.8VCC	-	VCC	V	
Logic Output	Low Voltage	Vol	0	-	0.2VCC	V	
Voltage	High Voltage	Vон	0.8VCC	1	-	V	

3.2 Driving Backlight

Item	Sym.	Min	Тур.	Max	Unit	Note
Backlight driving voltage	VF	-	3.2	1	٧	
Backlight driving current	lF	30	40	50	mA	
Backlight Power Consumption	WBL	-	128	-	mW	
Lift Time	-	-	50,000	-		Note 3

Note 1: (Unless specified, the ambient temperature Ta=25℃)

Note 2: The recommended operating conditions refer to a range in which operation of this product is guaranteed. Should this range is exceeded, the operation cannot be guaranteed even if the values may be without the absolute maximum ratings.

Note 3: If LED is driven by high current, high ambient temperature & humidity condition. The life time of LED will be reduced. Operating life means brightness goes down to 50% initial brightness. Typical operating life time is estimated data.



4.Optical Specifications

Optical characteristics are determined after the unit has been 'ON' and stable for approximately 30 minutes in a dark environment at 25 °C. The values specified are at an approximate distance 500mm from the LCD surface at a viewing angle of Φ and θ equal to $0^{\circ}.$

Mana.	Curren		Values		11-2:4	Note	
Item	Sym.	Min.	Тур.	Max.	Unit	Note	
1)Contrast Ratio	C/R	600	800	-		FIG.1	
2)Module Luminance	L	350	400	-	cd/m ²	FIG.1	
3)Response time	Tr+Tf	-	30	35	ms	FIG.2	
	θτ	-	80	-			
4)Viewing Angle	θ_{B}	-	80	-	D	FIG.3	
	θ_{L}	-	80	-	Degree		
	θ_{R}	-	80	-			
	Wx	0.250	0.290	0.330			
	Wy	0.265	0.305	0.345			
	Rx	-	-	-			
5)Oh	Ry	-	-	-			
5)Chromaticity	Gx	-	-	-			
	Gy	-	-	-			
	Вх	-	-	-			
	Ву	-	-	-			



♦ Measurement System

Notes:

1. Contrast Ratio(CR) is defined mathematically as:

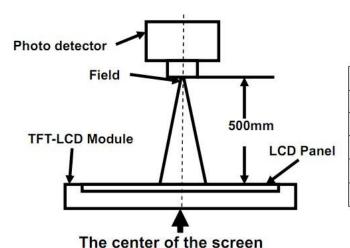
Surface Luminance with all white pixels

Contrast Ratio = ------

Surface Luminance with all black pixels

- 2. Surface luminance is the center point across the LCD surface 500mm from the surface with all pixels displaying white. For more information see FIG 1.
- 3. Response time is the time required for the display to transition from white to black (Rising Time, Tr) and from black to white (Falling Time, Tf). For additional information see FIG 2.
- 4. Viewing angle is the angle at which the contrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG 3.

FIG. 1 Optical Characteristic Measurement Equipment and Method



Item	Photo detector	Field
Contrast Ratio		
Luminance	CD 24	1°
Chromaticity	SR-3A	
Lum Uniformity		
Response Time	BM-7A	2°



FIG. 2 The definition of Response Time

The response time is defined as the following figure and shall be measured by switching the input signal for "black" and "white".

Response Time = Rising Time(Tr) + Falling Time(Tf)

- Rising Time(Tr): Full White 90% → Full White 10% Transmittance.
- Falling Time(Tf): Full White 10% → Full White 90% Transmittance.

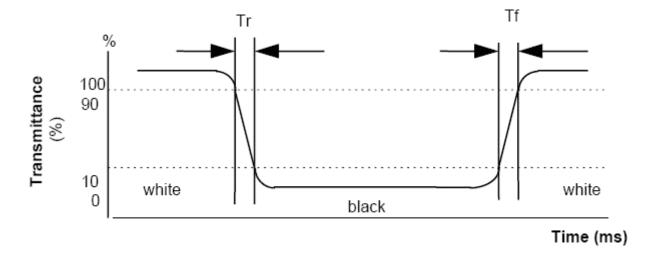
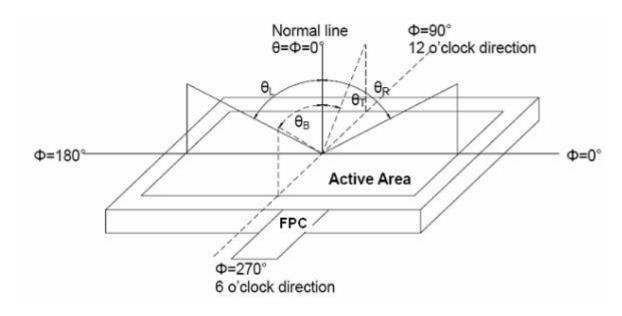


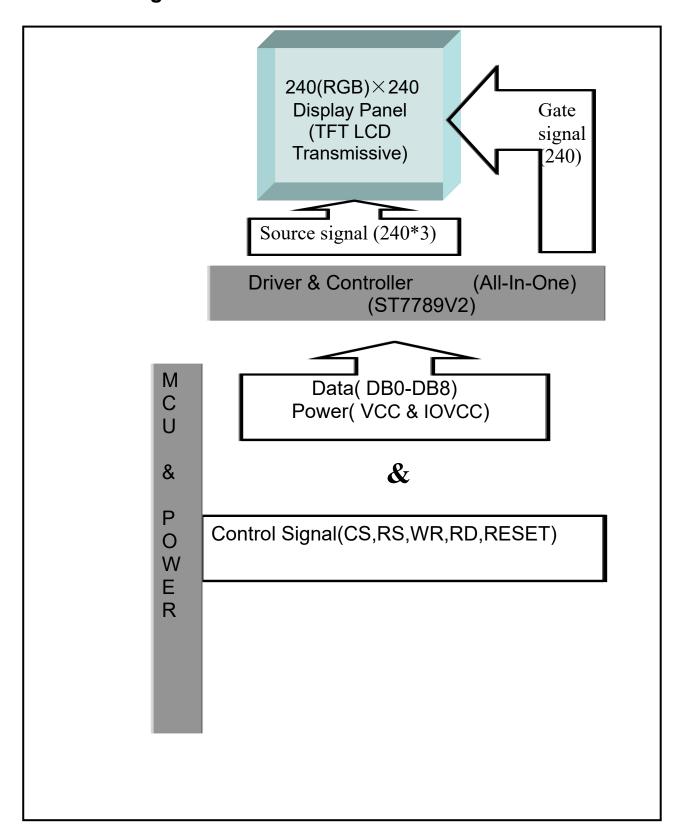
FIG. 3 The definition of Viewing Angle

Use Fig. 1(Test Procedure) under Measurement System to measure the contrast from the measuring direction specified by the conditions as the following figure.





5. Block Diagram





6. Pin Description

Item	Terminal	Functions
1	LEDA	The anode of the backlight
2	LEDK	The cathode of the backlight
3	IOVCC	Power input 1.8V-2.8V
4	GND	Power ground
5	VCC	Power input 2.8V
6	RESET	RESET PIN
7-15	DB8-DB0	Data bus
16	RD	Read signal pin
17	WR	Write signal pin
18	CS	Chip selected pin
19	RS	Command and data selected pin
20-24	GND	Power ground



7. Interface Timing Chart

7.1. Parallel Interface Characteristics

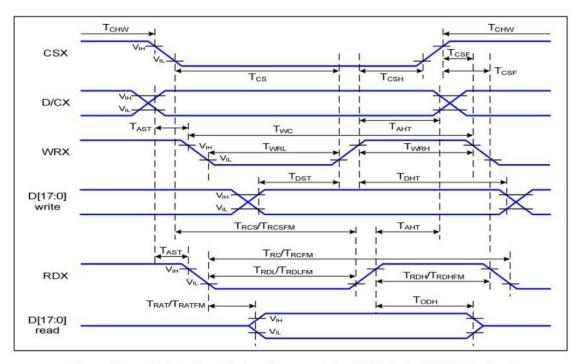


Figure 1 Parallel Interface Timing Characteristics (8080-Series MCU Interface)

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T _{AST}	Address setup time	0		ns	~
DICX	T _{AHT}	Address hold time (Write/Read)	10		ns	-
	T _{CHW}	Chip select "H" pulse width	0		ns	
CSX	T _{CS}	Chip select setup time (Write)	15		ns	
CSV	T _{RCS}	Chip select setup time (Read ID)	45		ns	
CSX	T _{RCSFM}	Chip select setup time (Read FM)	355		ns	-
	T _{CSF}	Chip select wait time (Write/Read)	10		ns	
T _{CSH}		Chip select hold time	10		ns	
WRX	T _{WC}	Write cycle	66		ns	
	T _{WRH}	Control pulse "H" duration	15		ns	
	T _{WRL}	Chip select setup time (Write) Chip select setup time (Read ID) Chip select setup time (Read FM) Chip select setup time (Read FM) Chip select wait time (Write/Read) Chip select wait time (Write/Read) Chip select hold time Write cycle Control pulse "H" duration Control pulse "L" duration Read cycle (ID) Control pulse "H" duration (ID) Control pulse "H" duration (ID) Control pulse "L" duration (ID) Read cycle (FM) Control pulse "H" duration (ID) Read cycle (FM) Control pulse "H" duration (FM) Control pulse "H" duration (FM)				
	T _{RC}	Read cycle (ID)	160		ns	
RDX (ID)	T _{RDH}	Control pulse "H" duration (ID)	90		ns	When read ID data
	T _{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX -	T _{RCFM}	Read cycle (FM)	450		ns	When read from
	T _{RDHFM}	Control pulse "H" duration (FM)	90		ns	frame memory
(I IVI)	T _{RDLFM}	Control pulse "L" duration (FM)	355		ns	name memory
D[17:0]	T _{DST}	Data setup time	10		ns	For CL=30pF



T _{DHT}	Data hold time	10		ns
T _{RAT}	Read access time (ID)		40	ns
T _{RATFM}	Read access time (FM)		340	ns
T _{ODH}	Output disable time	20	80	ns

Table 4 8080 Parallel Interface Characteristics

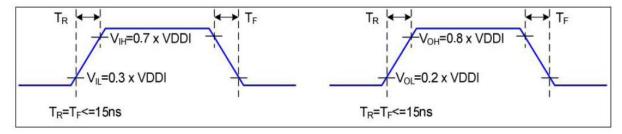


Figure 2 Rising and Falling Timing for I/O Signal

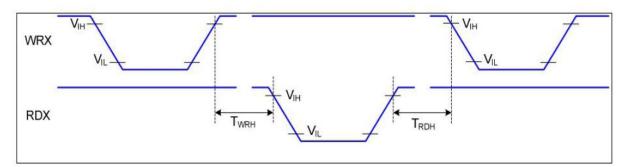


Figure 3 Write-to-Read and Read-to-Write Timing

Note: The rising time and falling time (Tr, Tf) of input signal and fall time are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.



7.2 Reset Operation

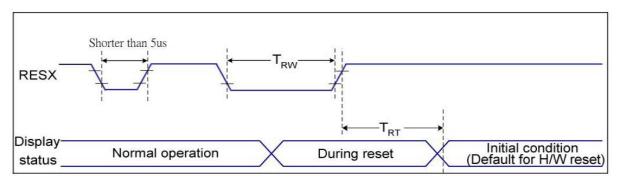


Figure 7 Reset Timing

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25 $^{\circ}$

Related Pins	Symbol	Parameter	MIN	MAX	Unit
	TRW	Reset pulse duration	10	=	us
RESX	TRT	Deset sensel	-	5 (Note 1, 5)	ms
	IKI	Reset cancel		120 (Note 1, 6, 7)	ms

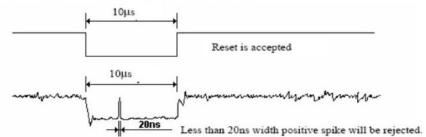
Table 9 Reset Timing

Notes:

- The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
 - 2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action	
Shorter than 5us	Reset Rejected	
Longer than 9us	Reset	
Between 5us and 9us	Reset starts	

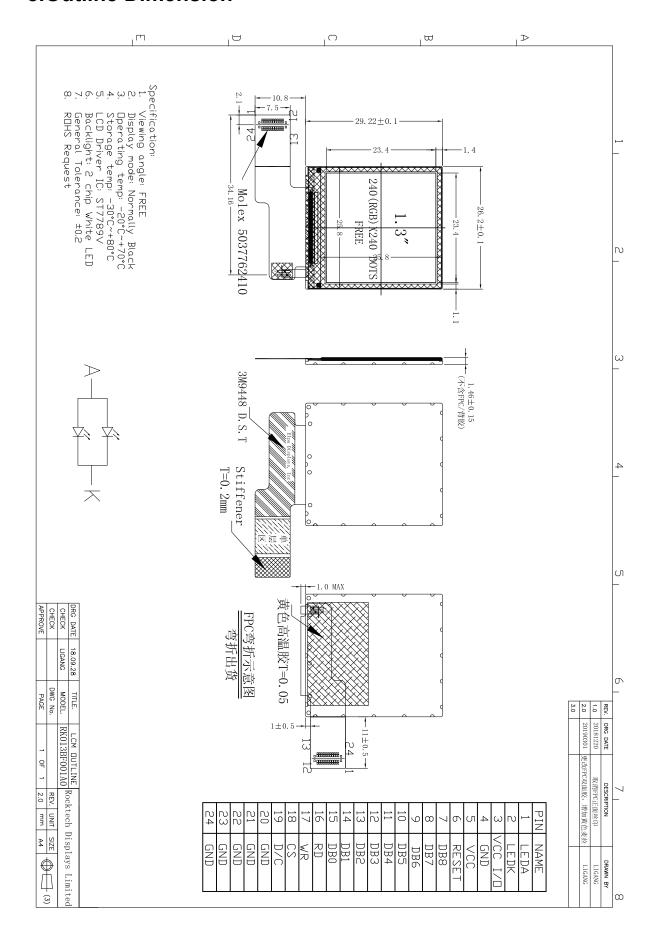
- 3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.
 - 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.



8.Outline Dimension





9. Reliability and Inspection Standard

No.	Test Item		Test Conditions	Remark
1	High Temperature	Storage	80℃, 120Hr	Note
		Operation	70 ℃, 120 Hr	Note
2	Low Temperature	Storage	-30℃, 120Hr	Note
		Operation	-20℃, 120Hr	
3	High Temperature and High Humidity		40℃, 90%RH, 120Hr	Note
4	Thermal Cycling Test(No operation)		-20℃ for 30min, 70℃ for 30 min. 100 cycles. Then test at room temperature after 1 hour	Note
5	Vibration Test(No operation)		Frequency:10~55 HZ; Stroke:1.5 mm;Sweep:10HZ~55HZ~10HZ; 2hours for each direction of X, Y, Z(6 hours for total)	
6	Package Drop Test		Height:60 cm,1 corner, 3 edges, 6 surfaces	
7	Electro Static Discharge		\pm 2KV,Human Body Mode, 100pF/1500 Ω	

Note:

- 1) Sample quantity for each test item is 5~10pcs.
- 2) Note 4: Before cosmetic and function test, the product must have enough recovery time, at least 2 hours at room temperature.



10.PRECAUTIONS FOR USING LCD MODULES

Handing Precautions

- (1) The display panel is made of glass and polarizer. As glass is fragile, it tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact.
- (2) If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.
- (3) Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary. Do not touch the display with bare hands. This will stain the display area and degraded insulation between terminals (some cosmetics are determined to the polarizer).
- (4) The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming is contacting with room temperature air.
- (5) If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents
 - Isopropyl alcohol
 - Ethyl alcohol

Do not scrub hard to avoid damaging the display surface.

- (6) Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.
 - Water
 - Ketone
 - Aromatic solvents

Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading. Avoid contacting oil and fats.

- (7) Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.
- (8) Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.
- (9) Do not attempt to disassemble or process the LCD module.
- (10) NC terminal should be open. Do not connect anything.
- (11) If the logic circuit power is off, do not apply the input signals.
- (12) Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.
 - Do not alter, modify or change the shape of the tab on the metal frame.
 - Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
 - Do not damage or modify the pattern writing on the printed circuit board.
 - Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal



connector.

- Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
- Do not drop, bend or twist LCM.

Storage Precautions

When storing the LCD modules, the following precaution is necessary.

- (1) Store them in a sealed polyethylene bag. If properly sealed, there is no need for the dessicant.
- (2) Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C.
- (3) The polarizer surface should not come in contact with any other objects. (We advise you to store them in the container in which they were shipped).

Others

Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature. If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

- Exposed area of the printed circuit board.
- -Terminal electrode sections.